

March 1 – 4, 2026

SPONSORSHIP EXHIBITION PROSPECTUS

ORGANIZERS









TECHNICAL SPONSORS



SUPPORTING ORGANIZATIONS











March 1 – 4, 2026, SPICE Convention Centre, Penang, Malaysia

INVITATION FROM THE GENERAL CHAIRS

On behalf of the Organizing Committee, we are pleased to invite you to support the IEEE Electron Devices Technology and Manufacturing Conference (EDTM) 2026, which will be held in the lovely island Penang, Malaysia, who is also known as "Silicon Valley of the East" from March 1–4, 2026. IEEE Electron Devices Society (EDS) started this fully sponsored Electron Devices Technology and Manufacturing (EDTM) conference and inaugurated the 1st EDTM 2017 conference in Toyama, Japan during February 28 – March 2, 2017. EDTM 2026 marks a significant milestone as we celebrate the 10th Anniversary of this premier international conference. We warmly welcome you to join us in commemorating this special occasion and contributing to the continued success of the EDTM series.

EDTM 2026 Themed is "Emerging Semiconductor Devices and Manufacturing Technologies: The Next Era of Innovation", will showcase cutting-edge advancements and explore the future of semiconductor technology.

EDTM serves as a global platform for industry leaders, researchers, and innovators to exchange breakthroughs in microelectronics, semiconductors, and device manufacturing. As a sponsor, your organization will gain unparalleled visibility among experts, decision-makers, and future leaders from both academia and industry.

A lineup of distinguished keynote speakers, renowned for their technical excellence and visionary insights, will headline the event.

Your support plays a vital role in the success of EDTM and helps us foster technical excellence, collaboration, and innovation across the global electronics community. We offer a variety of sponsorship packages designed to maximize your brand exposure and engagement with attendees.

We look forward to your participation and support in making EDTM 2026 a resounding success. We warmly invite you to join us in shaping the future of technology at EDTM 2026. Together, let's make this a landmark event for the field.

For more details on sponsorship opportunities, please feel free to contact us or visit https://ieee-edtm.org/ or email to secretariat@ieee-edtm.org/.

Thank you for your consideration, and we look forward to your valued partnership.

Warm regards,

Dr Bernard Lim General Chair, EDTM 2026 berna_rd@ieee.org



Dr Samar Saha General Co-Chair, EDTM 2026 samarsah@pacbell.net





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ABOUT EDTM 2026

The 10th anniversary of the Electron Devices Technology and Manufacturing (EDTM) Conference, fully sponsored by the IEEE Electron Devices Society (EDS), will be celebrated with a special four-day event in Penang, Malaysia, from March 1 to 4, 2026.

Since its inception, EDTM has grown into a global platform for innovation, drawing participation from leading industry leaders, engineers, and academicians across the world who are working at the forefront of cutting-edge semiconductor devices and technologies.

While many in the community are familiar with the IEEE International Electron Devices Meeting (IEDM), the flagship venue for groundbreaking research in device physics and microelectronics, EDTM was conceived to address the equally critical need for a holistic, end-to-end view of technology development, spanning materials, process integration, manufacturing, packaging, and system-level integration.

As device miniaturization approaches its physical and economic limits, the performance of integrated circuits and systems continues to advance through innovations in materials, advanced packaging, heterogeneous integration, and design-technology co-optimization. To accelerate progress in these areas, a dedicated forum for deep technical exchange was essential, particularly in Asia, which serves as the global hub for semiconductor manufacturing.

Recognizing this, the IEEE EDS launched EDTM, with the inaugural conference held in Toyama, Japan, from February 28 to March 2, 2017. Since then, the conference has rotated through major Asian semiconductor regions, serving as a dynamic venue for addressing challenges and opportunities across the entire semiconductor ecosystem.

Similar in vision to IEDM, a sister flagship conference, EDTM is now recognized as one of the world's premier forums for reporting breakthroughs in a wide range of cutting-edge technologies. These include nanometer-scale CMOS technology, advanced memory and storage solutions, and quantum and nanoelectronic devices. The forum also highlights innovations in displays, sensors, and MEMS technologies, as well as optoelectronic and energy-harvesting devices. Additionally, EDTM covers advancements in high-speed and power semiconductor devices, along with process technology, modeling, and simulation techniques.

The 2026 edition in Penang marks a decade of innovation, collaboration, and impact, bringing together a global community dedicated to enabling the future of electronics through advanced device technology and manufacturing solutions.



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GLOBAL EXPOSURE

EDTM has been fully sponsored by the IEEE EDS since 2017, recognizing its strong potential to engage and connect with global audiences.

EDTM serves as a premier platform for researchers, engineers, and innovators to showcase and present their latest work, while gaining international visibility, recognition, and valuable feedback from leading experts in the field.

Accepted papers will be published in IEEE Xplore, increasing the visibility, impact, and credibility of your work within the global research community.

NETWORKING OPPORTUNITES

EDTM serves as a hub for building connections with global leaders from academia and industry, offering attendees valuable opportunities to network with experts, potential collaborators, and industry partners. These interactions can lead to meaningful partnerships, research collaborations, and business opportunities, enhancing both academic and professional growth.

REASONS TO PARTICIPATE

GAIN INSIGHTS FROM WORLD-CLASS KEYNOTE SPEAKERS AND PANELS

By attending EDTM, participants gain valuable insights directly from leading visionaries and experts who are shaping the future of electron devices, semiconductors, AI hardware, and advanced manufacturing. The conference offers in-depth sessions and technical presentations that help attendees stay current with the latest advancements, trends, and innovations driving the industry forward.

Showcasing Innovations and Solutions

The exhibition component of EDTM offers companies a valuable platform to showcase their latest technologies, products, and solutions in areas such as semiconductors, device manufacturing, materials, and automation. It also creates opportunities for technology scouting, business development, and strategic partnerships with attendees from across the global tech ecosystem.



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SPONSORSHIP OPPORTUNITIES

EARLY BIRD DISCOUNT: Submit your booking form by 1 October 2025 to enjoy a 5% discount

		Special	Diamond	Platinum	Gold	Silver	Bronze	Exhibition Only
Package	USD	25,000	15,000	13,000	10,000	6,500	4,000	2,500
Entitlements	MYR	100,000	60,000	52,000	40,000	26,000	16,000	10,000
Display of Sponsor's Logo on EDTM Website		V	$\sqrt{}$	$\sqrt{}$	V	V		√
Sponsor's Logo on Backdrop/Banner at Hotels and Other Sites.		V	$\sqrt{}$	V	V	V	√	V
Special Mention of Sponsorship during Opening Ceremony		V	V	V	V	V	-	-
Sponsor's Logo on the Cover of the Program Schedule/Abstract Book/		V	$\sqrt{}$	V	V	-	-	-
Up to 60-sec Company Video on Screens in Exhibition Hall		V	$\sqrt{}$	V	V	-	-	-
Acknowledgement on our Social Media Platforms		√	$\sqrt{}$	V	-	-	-	-
A 20-minute Technical Talk		V	$\sqrt{}$	-	-	-	-	-
Advertisement of the Company in the Program eBooklet		4 Pages	2 Pages	2 Pages	1 Page	1 Page	1/2 Page	-
Number of Complimentary Full Conference Registration		8	5	4	3	2	1	-
Number of Complimentary Tutorial/Short Course Registration		8	4	3	2	1	-	-
Number of Complementary Exhibition Booths (3m x 3m)		4	3	2	1	-	-	1

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BRANDING OPPORTUNITIES

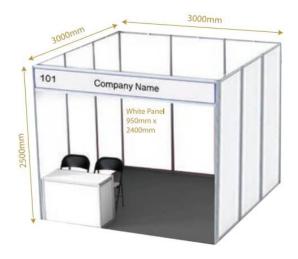
EARLY BIRD DISCOUNT: Submit your booking form by 1 October 2025 to enjoy a 5% discount

Branding Opportunities	Cost
 Conference Bag (Exclusive) Logo printed on conference bags together with the conference logo Logo acknowledgement and link to company URL on conference website 	USD 5,000 (MYR20,000)
Conference Lanyard (Exclusive) Logo printed on lanyard together with the conference logo Logo acknowledgement and link to company URL on conference website	USD 3,000 (MYR12,000)
 Welcome Reception (Exclusive) Acknowledgment of sponsorship at prominent locations during the Welcome Reception Logo acknowledgement and link to company URL on conference website 	USD 3,000 (MYR12,000)
 Lunch Sponsorship (Per Day) Acknowledgment of sponsorship at prominent locations during lunch* Logo acknowledgement and link to company URL on conference website *Selection of day on a first-come-first-served basis, subject to organizer's approval. 	USD 2,000 (MYR8,000)
 Coffee Break Sponsorship (Per Day) Acknowledgment of sponsorship at selected coffee break session* Logo Acknowledgement and link to company URL on conference website *Selection of coffee break on a first-come-first-served basis, subject to organizer's approval. 	USD 1,000 (MYR4,000)
 Pull-up Banner One (01) self-prepared pull up banner (size up to 800mmW x 2000mmH) to be placed at organizer's discretion 	USD 1,000 (MYR4,000)

1 STANDARD BOOTH: 3M (WIDTH) X 3M (DEPTH) X 2.5M (HEIGHT)

Inclusions

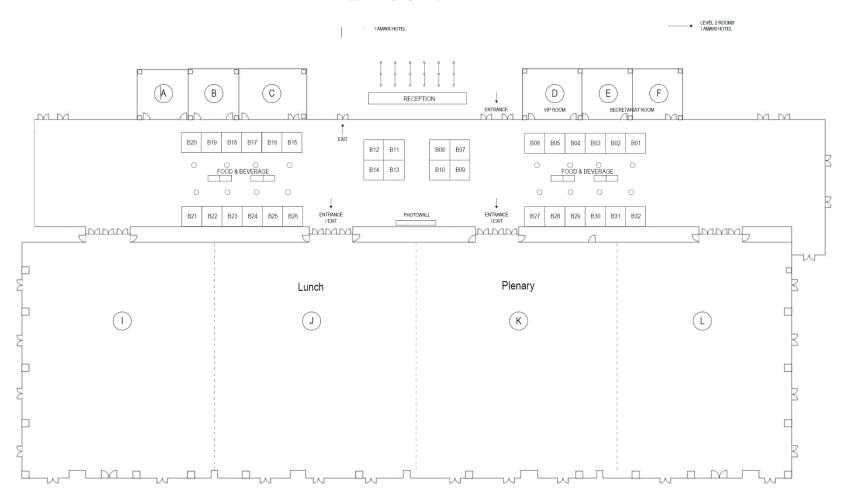
- E-system Table x 1 unit
- Folding Chair x 2 units
- Company Name Cutout x 1 unit PVC Sticket 2.75" (H)
- Waste Basket x 1 unit
- Fluorescent Light x 2 nos
- 13A Power Point x 1 no





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LAYOUT PLAN



Floorplan is subject to changes at the Organizer's discretion



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ALLOCATION OF EXHIBITION SPACE

Space allocation will be given on a "first-come-first served" basis. A completed Booking Form should be emailed to the secretariat. Upon receipt of the Booking Form, space will be reserved according to availability, and an invoice will be sent via email. Space allocations will be confirmed when the payment is received.

Exhibitor Registration All exhibitors are required to be registered and will receive a badge displaying the exhibiting company's name. According to the package booked, exhibitor badges will be complimentary up to the number allocated. Exhibitor registrations allow access to the exhibition area only and shall be used by company staff only. Complimentary registration to attend all the EDTM 2026 events will be provided according to the packaged booked.

Exhibitors' Manual: An Exhibitors' Manual providing all the information for the preparation of the booth will be sent 2 months prior to EDTM 2026.

Terms & Conditions: The Terms and Conditions of exhibiting are included in this Prospectus. Please note that signing of the BOOKING FORM indicates acceptance of these Terms and Conditions. The Booking Form will be held as a valid liable contract, by which both parties will be bound.

BOOKING PROCEDURES AND PAYMENT INFORMATION

Invoice: Once the Booking Form is received, an invoice will be sent.

Terms of Payment: 100% upon receipt of the invoice.

Payment Method: Bank Transfer (bank charges are the responsibility of the payer)

International Bank (USD):

Wire Information

Bank Name: Wells Fargo Bank N.A Address: 123 South Broad Street

City: Philadelphia State: PA 19109

Account Name: Institute of Electrical and Electronics Engineers

Account #: 21570000000657720 ABA/Routing #: 121000248

Swift Address: WFBIUS6S (for international wires)

Local Bank (MYR):

Bank Name: Malayan Banking Berhad Bank Address: Shah Alam Main Branch,

10 Persiaran Perbandaran Section 14 40000 Shah Alam.

40702 Shah Alam, Selangor SWIFT Code: MBBEMYKL

Account Holder's Name: IEEE Malaysia Section

Account Number: 562106993399

Cancellation/Modification Policy Cancellation or modification of sponsorship items must be made in writing to the Conference Secretariat for the consideration of the committee.

The Organizer shall retain:

- 50% of the agreed package amount if the cancellation or modification is made on or before 31 December 2025;
- 100% of the agreed package amount if the cancellation or modification is made after 31 December 2025



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BOOKING FORM

Company Name				_				
Contact Person								
Designation								
Tel (O)			Mobile					
Email	Website							
Address								
Country	Postal Code							
Packages	Price (USD)	Price (MYR)	Select the package(s)	Remarks, if any (E.g. Quantity / Preferred Day)				
Special Sponsorship	25,000	100,000						
Diamond Sponsorship	15,000	60,000						
Platinum Sponsorship	13,000	52,000						
Gold Sponsorship	10,000	40,000						
Silver Sponsorship	6,500	26,000						
Bronze Sponsorship	4,000	16,000						
Exhibition Only	2,500	10,000						
Conference Bag (Exclusive)	5,000	20,000						
Conference Lanyard (Exclusive)	3,000	12,000						
Welcome Reception (Exclusive)	3,000	12,000						
Lunch Sponsorship (Per Day)	2,000	8,000						
Coffee Break Sponsorship (Per Day)	1,000	4,000						
Pull-up Banner	1,000	4,000						
Payment Method (Select one)	Internationa	Local	Bank (MYR) \square					
Signature		Da	ate					



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TERMS AND CONDITIONS

These terms are the contractual agreement between the Organizer and the Sponsor / Exhibitor.

Application to Participate

Applications to participate will only be considered if submitted via the completed Booking Form. Registration will be confirmed subject to availability of space. Applicants will be notified in writing regarding the acceptance or rejection of their application. In the event of rejection, any payments made will be fully refunded. Upon acceptance, the Sponsor / Exhibitor agrees to be bound by the Terms and Conditions outlined in the prospectus.

Obligations and Rights of the Sponsor / Exhibitor

Registration implies full acceptance by the Sponsor / Exhibitor of the sponsorship regulations. Any infringement of these regulations may lead to immediate withdrawal of the right to participate in the Conference without compensation or refund of sums already paid, and without prejudice to the Sponsor / Exhibitor.

By submitting the Booking Form to participate, the Sponsor / Exhibitor made a final and irrevocable commitment to occupy the space / items allocated and to maintain the installation until the date and time fixed for closure of the event.

The Sponsor / Exhibitor may only present on their stand or space the materials, products or services described in the application to participate.

No advertising on behalf of firms not exhibiting is permitted in any form whatsoever. Transfer or sub-letting of all or part of the allocated spaces is prohibited.

Obligation and Rights of Organizer

The Organizer undertakes to allocate sponsorship items space based on the preference expressed by applicants. Application will be considered in order of receipt of booking forms accompanied by payment.

The Organizer reserves the right, in case of absolute necessity, to modify the positioning of stands, with no obligation to provide compensation to Sponsors.

Liability Insurance

Equipment and all related display materials installed by Sponsors / Exhibitors are not insured by the Organizer, and the Organizer under no circumstances will be liable for any loss, damage or destruction caused to equipment, goods or property belonging to Sponsors / Exhibitors. The Sponsor / Exhibitor agrees to be responsible for their property and staff manning the space and for the property of their agents and for any third party who may visit the space. The Sponsor / Exhibitor shall hold harmless the Organizer from any and all damages/claims including those usually covered by a fire and extended coverage policy. The Sponsor / Exhibitor will purchase insurance policies for the above listed damages.

Exhibition Regulations

The Exhibition Chair, acting under the direction of the Organizing Committee, has the final decision as to the acceptability of displays. Sponsors are not to share with others any space allotted to them without prior written consent by the Exhibition Chair.

The Organizer reserves the right to alter the general layout or limit the space allotted to each Sponsor / Exhibitor, postpone the exhibition or transfer it to another site if unforeseen circumstances warrant such action. Should any contingency prevent the holding of the exhibition, the Organizer will not be held liable for expenses incurred other than the cost of exhibit space rental fees. All exhibits are to be displayed within the allocated spaceo avoid blocking aisles, obstructing adjoining booths, damaging the premises or the leased equipment. Sponsors / Exhibitors are kindly requested to allow sufficient see-through areas, which ensure clear views of surrounding exhibits.

Sponsors / Exhibitors are responsible for the cost and execution of the design, installation and delivery of their display and its removal from the exhibition site.

Flammable materials are not to be used. Equipment displayed or demonstrated must be installed with strict adherence to safety measures.

Sponsors / Exhibitors undertake to observe the timetable designated for completion of their display before the exhibition opening and it's dismantling at the close of the exhibition. No dismantling or packing of the display before the designated hour. It is the Sponsor's / Exhibitor's responsibility to pack and remove or consign for shipment all items of value prior to leaving their exhibit unattended, otherwise the Organizer will arrange for their removal at the Sponsor's / Exhibitor's risk and expenses.

Sponsors / Exhibitors are obliged to ensure that their stands are permanently staffed during the exhibition opening hours.

Participation by Sponsors / Exhibitors is dependent upon compliance with all rules, regulations and conditions stated herein.

Access to the exhibition is authorised on presentation of a badge issued by the Organizer. Badges will not be mailed in advance and may be collected from the Registration desk onsite.

The Organizer ensures daily cleaning of the aisles. Sponsors / Exhibitors are responsible for the cleaning of their stands. The provision of refreshments for the participants by Sponsors / Exhibitors is only permitted if the catering regulations of the exhibition building concerned are observed.

Exhibition areas and fittings made available to Sponsors / Exhibitors must be handed back in their original condition. In case of damage or loss of equipment provided, or damage to areas occupied, repair and replacement will be charged to the Sponsor / Exhibitor.

Any special decoration or fittings must be submitted to the Organizer for prior authorisation.

Advertising panels and display are not permitted outside the exhibition areas allotted to Sponsors / Exhibitors.



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To learn more, visit http://ieee-edtm.org/

CONTACT US

EDTM 2026 Conference Secretariat

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E: jasmine@jjayes.com

CC: secretariat@ieee-edtm.org